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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of: Kie Y. Ahn et al.

Title: POROUS SILICON OXYCARBIDE INTEGRATED CIRCUIT INSULATOR

Attorney Docket No.: 303.377US3

jc882 U.S. PTO
09/909532**PATENT APPLICATION TRANSMITTAL****BOX PATENT APPLICATION**

Commissioner for Patents

Washington, D.C. 20231

We are transmitting herewith the following attached items and information (as indicated with an "X"):

☒ Return postcard.☒ **CONTINUATION** of prior Patent Application No. 08/950,319 (under 37 CFR § 1.53(b)) comprising:☒ Specification (18 pgs, including claims numbered 1 through 48 and a 1 page Abstract).☒ Formal Drawing(s) (4 sheets).☒ Copy of signed Declaration (6 pgs) from prior application.☒ Incorporation by Reference: *The entire disclosure of the prior application, from which a copy of the oath or declaration is supplied herewith, is considered as being part of the disclosure of the accompanying application and is hereby incorporated by reference therein.*☒ Check in the amount of \$1,486.00 to pay the filing fee.Prior application is assigned of record to Micron Technology, Inc..Information Disclosure Statement (1 pg), Form 1449 (2 pgs). References NOT enclosed, cited in prior application.Preliminary Amendment (7 pgs).

The filing fee has been calculated below as follows:

	No. Filed	No. Extra	Rate	Fee
TOTAL CLAIMS	32 - 20 =	12	x 18 =	\$216.00
INDEPENDENT CLAIMS	10 - 3 =	7	x 80 =	\$560.00
[] MULTIPLE DEPENDENT CLAIMS PRESENTED				\$0.00
BASIC FEE				\$710.00
TOTAL				\$1,486.00

Please charge any additional required fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

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This paper or fee is being deposited on the date indicated above with the United States Postal Service pursuant to 37 CFR 1.10, and is addressed to The Commissioner for Patents, Box Patent Application, Washington, D.C. 20231.